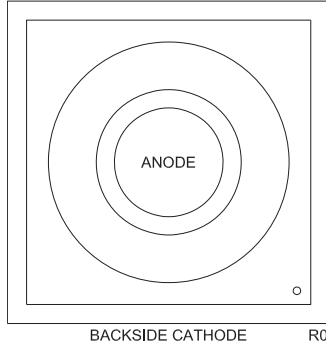


# CPD66X-CLL459A

## Low Leakage Diode Die

### 0.2 Amp, 200 Volt

The CPD66X-CLL459A is a silicon 0.2 Amp, 200 Volt diode designed for low leakage applications.



#### MECHANICAL SPECIFICATIONS:

Die Size	17.5 x 17.5 MILS
Die Thickness	5.9 MILS
Anode Bonding Pad Size	7.0 MILS DIAMETER
Top Side Metalization	Al – 30,000Å
Back Side Metalization	Au-As – 9,000Å
Scribe Alley Width	2.0 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	54,848

#### MAXIMUM RATINGS: ( $T_A=25^\circ\text{C}$ )

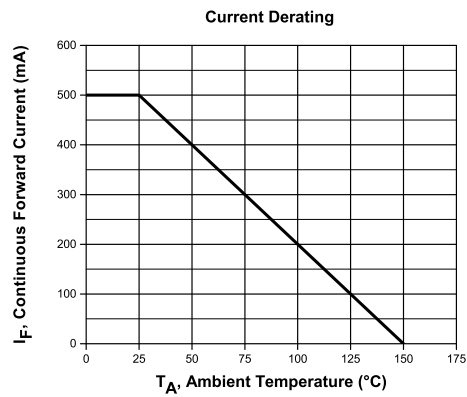
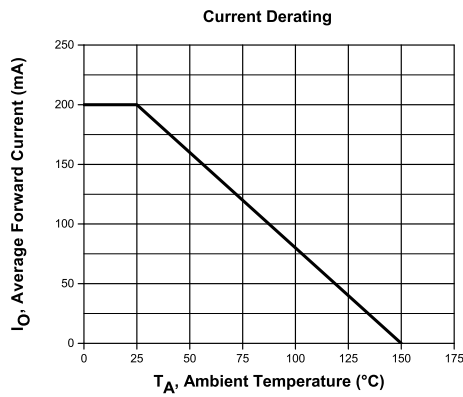
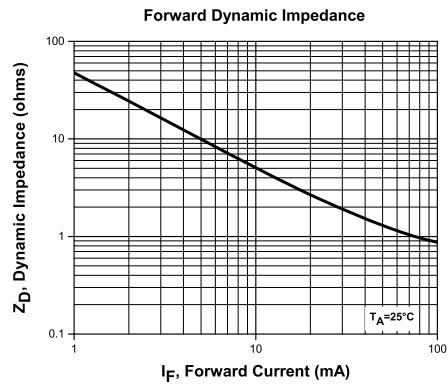
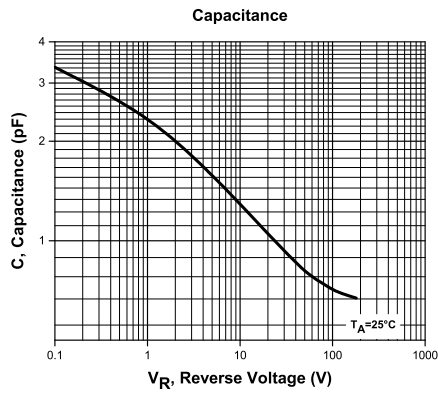
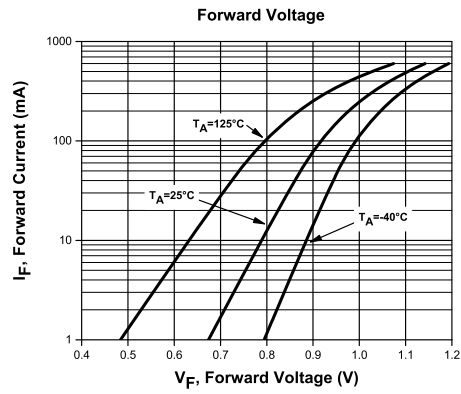
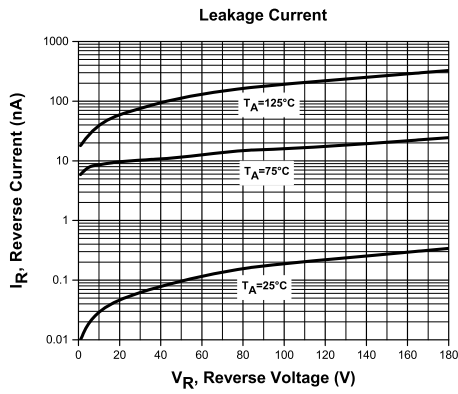
	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	$V_{RRM}$	200	V
Peak Working Reverse Voltage	$V_{RWM}$	175	V
Average Forward Current	$I_O$	200	mA
Continuous Forward Current	$I_F$	500	mA
Peak Forward Surge Current, $t_p=1.0\mu\text{s}$	$I_{FSM}$	4.0	A
Operating and Storage Junction Temperature	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

#### ELECTRICAL CHARACTERISTICS: ( $T_A=25^\circ\text{C}$ unless otherwise)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
$I_R$	$V_R=175\text{V}$		25	nA
$BV_R$	$I_R=100\mu\text{A}$	200		V
$V_F$	$I_F=100\text{mA}$		1.0	V
$C_J$	$V_R=0, f=1.0\text{MHz}$		6.0	pF

# CPD66X-CLL459A

## Typical Electrical Characteristics



## BARE DIE PACKING OPTIONS

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### BARE DIE IN TRAY (WAFFLE) PACK

**CT:** Singulated die in tray (waffle) pack.  
(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).  
(example: CP211-PART NUMBER-CM)

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### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.  
(example: CP211-PART NUMBER-WN)

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### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring,  
100% tested with reject die inked.  
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:  
[www.centrasemi.com/bdspecs](http://www.centrasemi.com/bdspecs)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.  
145 Adams Avenue  
Hauppauge, NY 11788 USA  
Main Tel: (631) 435-1110  
Main Fax: (631) 435-1824  
Support Team Fax: (631) 435-3388  
[www.centrasemi.com](http://www.centrasemi.com)

**Worldwide Field Representatives:**  
[www.centrasemi.com/wwreps](http://www.centrasemi.com/wwreps)

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